

Product Change Notification / MFOL-19LRGK540

Date:

22-Dec-2021

Product Category:

General Purpose FPGAs

PCN Type:

Manufacturing Change

Notification Subject:

eSign# E000083716 Final Notice: Qualification of C194 lead frame material with 15.5 mm x 15.5 mm lead frame paddle size for selected Microsemi APA1000 FPGA device family available in MQFP 208L (28X28X3.4mm) package at ANAP assembly site.

Affected CPNs:

MFOL-19LRGK540_Affected_CPN_12222021.pdf MFOL-19LRGK540_Affected_CPN_12222021.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of C194 lead frame material with 15.5 mm x 15.5 mm lead frame paddle size for selected Microsemi APA1000 FPGA device family available in MQFP 208L (28X28X3.4mm) package at ANAP assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change						
Assembly Site	Amkor Technology Philippine (P1/P2), INC.	Amkor Technology Philippine (P1/P2), INC.						
	(ANAP)	(ANAP)						
Wire Material	Au	Au						
Die Attach Material	3230	3230						
Molding Compound Material	G700M	G700M						
Lead frame material	C7025	C194						
Lead frame Paddle Size	16 mm x 16 mm	15.5 mm x 15.5 mm						
Lead frame design	See pre and post change comparison							

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying C194 lead frame material with 15.5 mm x 15.5 mm lead frame paddle size at ANAP assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: January 12, 2022

Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2021					>	January 2022					
Workweek	49	50	51	52	53		01	02	03	04	05	
Qual Report Availability				Х								
Final PCN Issue Date				Х								
Estimated Implementation Date									Х			

Method to Identify Change:

Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PA-231 Qualification of APA1000-PQG208 with Modified Leadframe Design and Assembly at Amkor Philippines.

Revision History: December 22, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_MFOL-19LRGK540 Pre and Post change summary.pdf PCN_MFOL-19LRGK540_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. MFOL-19LRGK540 - eSign# E000083716 Final Notice: Qualification of C194 lead frame material with 15.5 mm x 15.5 mm lead frame paddle size for selected Microsemi APA1000 FPGA device family available in MQFP 208L (28X28X3.4mm) package at ANAP assembly site.

Affected Catalog Part Numbers (CPN)

APA1000-PQG208 APA1000-PQG208X259 APA1000-PQG208X538 APA1000-PQG208A APA1000-PQG208M APA1000-PQG208I APA1000-PQG208IX538 APA1000-PQG208IX259